



STW56NM60N

N-channel 600 V, 0.05 Ω , 45 A TO-247
MDmesh™ II Power MOSFET

Preliminary data

Features

| Order code | V _{DSS} | R _{DS(on) max} | I _D |
|------------|------------------|-------------------------|----------------|
| STW56NM60N | 600 V | < 0.06 Ω | 45 A |

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the second generation of MDmesh™ technology. This revolutionary Power MOSFET associates a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. It is therefore suitable for the most demanding high efficiency converters.

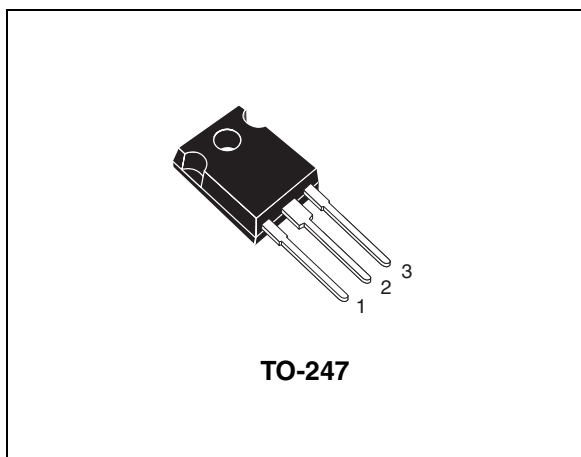


Figure 1. Internal schematic diagram

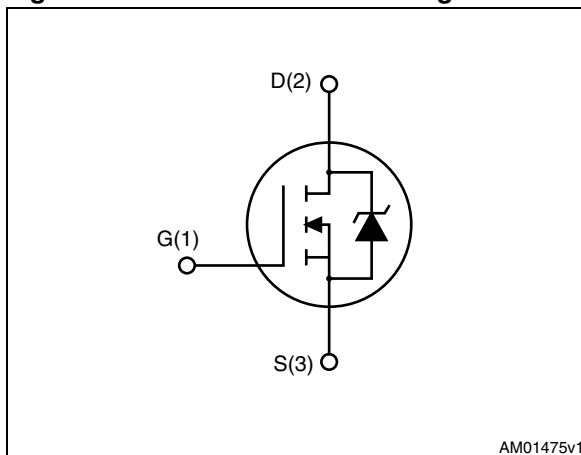


Table 1. Device summary

| Order code | Marking | Package | Packaging |
|------------|---------|---------|-----------|
| STW56NM60N | 56NM60N | TO-247 | Tube |

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1 Electrical ratings

Table 2. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|--|-------------|------|
| V_{DS} | Drain-source voltage ($V_{GS} = 0$) | 600 | V |
| V_{GS} | Gate-source voltage | ± 25 | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ °C}$ | 45 | A |
| I_D | Drain current (continuous) at $T_C = 100\text{ °C}$ | 28 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 180 | A |
| P_{TOT} | Total dissipation at $T_C = 25\text{ °C}$ | 300 | W |
| I_{AS} | Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max) | TBD | A |
| E_{AS} | Single pulse avalanche energy (starting $T_j=25\text{ °C}$, $I_D=I_{AS}$, $V_{DD}=50\text{ V}$) | TBD | mJ |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 15 | V/ns |
| T_{stg} | Storage temperature | - 55 to 150 | °C |
| T_j | Max. operating junction temperature | 150 | °C |

1. Pulse width limited by safe operating area

2. $I_{SD} \leq 11\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DS\text{ peak}} \leq V_{(BR)DSS}$, $V_{DD} = 80\% V_{(BR)DSS}$.

Table 3. Thermal data

| Symbol | Parameter | Value | Unit |
|----------------|--|-------|------|
| $R_{thj-case}$ | Thermal resistance junction-case max | 0.42 | °C/W |
| $R_{thj-amb}$ | Thermal resistance junction-ambient max | 50 | °C/W |
| T_l | Maximum lead temperature for soldering purpose | 300 | °C |

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|--|--|------|------|----------|--------------------------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage ($V_{GS} = 0$) | $I_D = 1\text{ mA}$, | 600 | | | V |
| I_{DSS} | Zero gate voltage drain current ($V_{GS} = 0$) | $V_{DS} = 600\text{ V}$ $V_{DS} = 600\text{ V}$, $T_C = 125\text{ °C}$ | | | 1 100 | μA μA |
| I_{GSS} | Gate-body leakage current ($V_{DS} = 0$) | $V_{GS} = \pm 20\text{ V}$ | | | 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$ | 2 | 3 | 4 | V |
| $R_{DS(on)}$ | Static drain-source on resistance | $V_{GS} = 10\text{ V}$, $I_D = 22.5\text{ A}$ | | 0.05 | 0.06 | Ω |

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------------------|-------------------------------|--|------|------|------|------|
| C_{iss} | Input capacitance | $V_{DS} = 50\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$ | - | 4800 | - | pF |
| C_{oss} | Output capacitance | | | 320 | | pF |
| C_{rss} | Reverse transfer capacitance | | | 4.5 | | pF |
| $C_{oss\text{ eq.}}^{(1)}$ | Equivalent output capacitance | $V_{GS} = 0$, $V_{DS} = 0\text{ to }480\text{ V}$ | - | TBD | - | pF |
| Q_g | Total gate charge | $V_{DD} = 480\text{ V}$, $I_D = 45\text{ A}$, $V_{GS} = 10\text{ V}$, <i>(see Figure 3)</i> | - | 150 | - | nC |
| Q_{gs} | Gate-source charge | | | TBD | | nC |
| Q_{gd} | Gate-drain charge | | | TBD | | nC |

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 300\text{ V}$, $I_D = 22\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ (see Figure 2) | - | TBD | - | ns |
| t_r | Rise time | | | TBD | | ns |
| $t_{d(off)}$ | Turn-off delay time | | | TBD | | ns |
| t_f | Fall time | | | TBD | | ns |

Table 7. Source drain diode

| Symbol | Parameter | Test conditions | Min | Typ. | Max | Unit |
|-----------------|-------------------------------|--|-----|------|-----|---------------|
| I_{SD} | Source-drain current | | - | | 45 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | | | 180 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 45\text{ A}$, $V_{GS} = 0$ | - | | 1.6 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 45\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ (see Figure 4) | - | TBD | | ns |
| Q_{rr} | Reverse recovery charge | | | TBD | | μC |
| I_{RRM} | Reverse recovery current | | | TBD | | A |
| t_{rr} | Reverse recovery time | $I_{SD} = 45\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 4) | - | TBD | | ns |
| Q_{rr} | Reverse recovery charge | | | TBD | | μC |
| I_{RRM} | Reverse recovery current | | | TBD | | A |

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

3 Test circuits

Figure 2. Switching times test circuit for resistive load

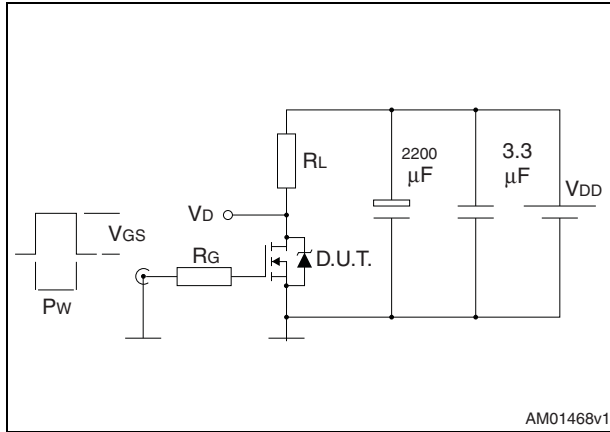


Figure 3. Gate charge test circuit

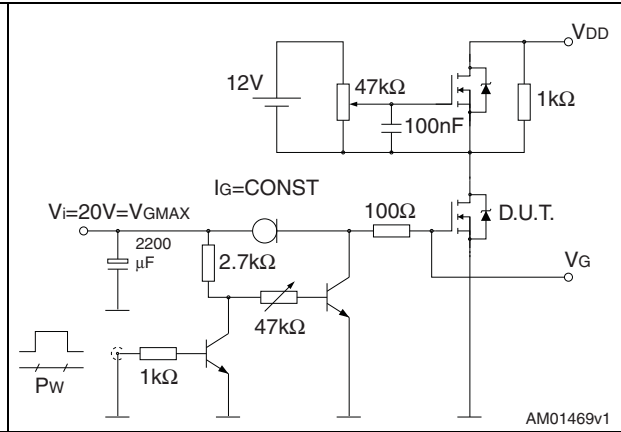


Figure 4. Test circuit for inductive load switching and diode recovery times

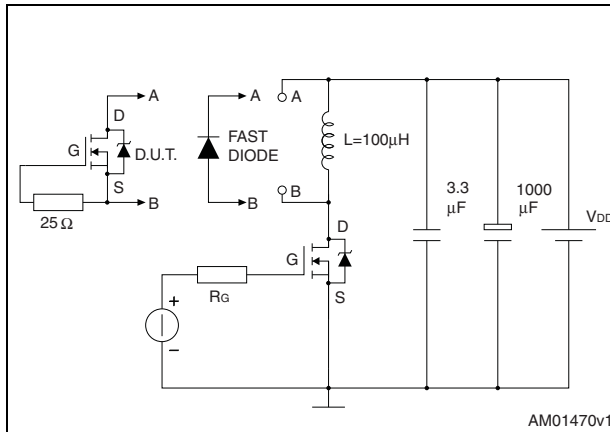


Figure 5. Unclamped inductive load test circuit

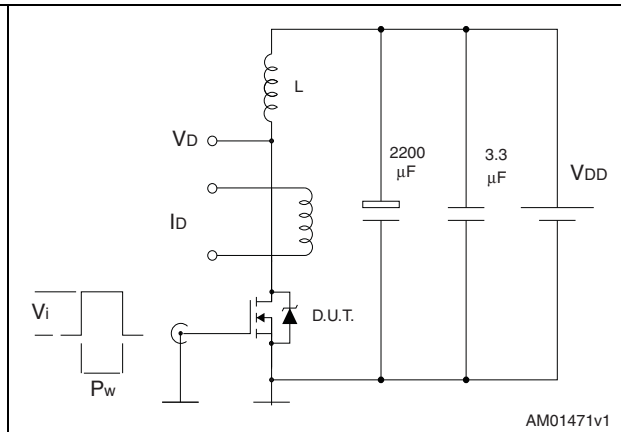


Figure 6. Unclamped inductive waveform

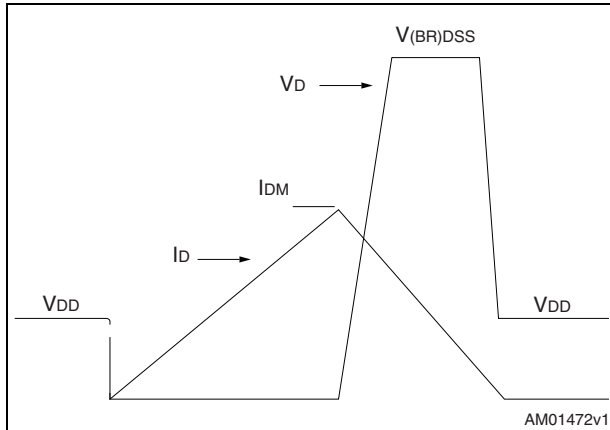
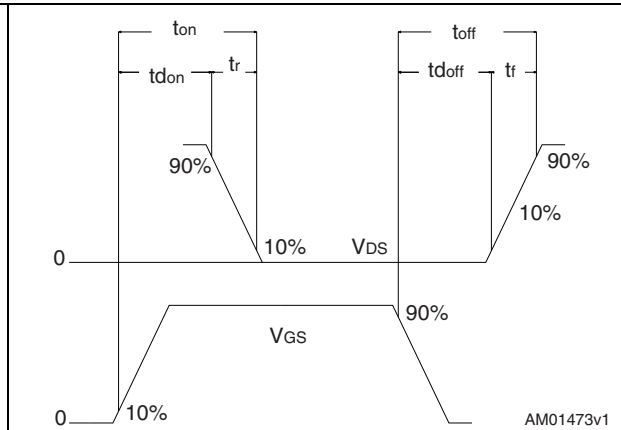


Figure 7. Switching time waveform



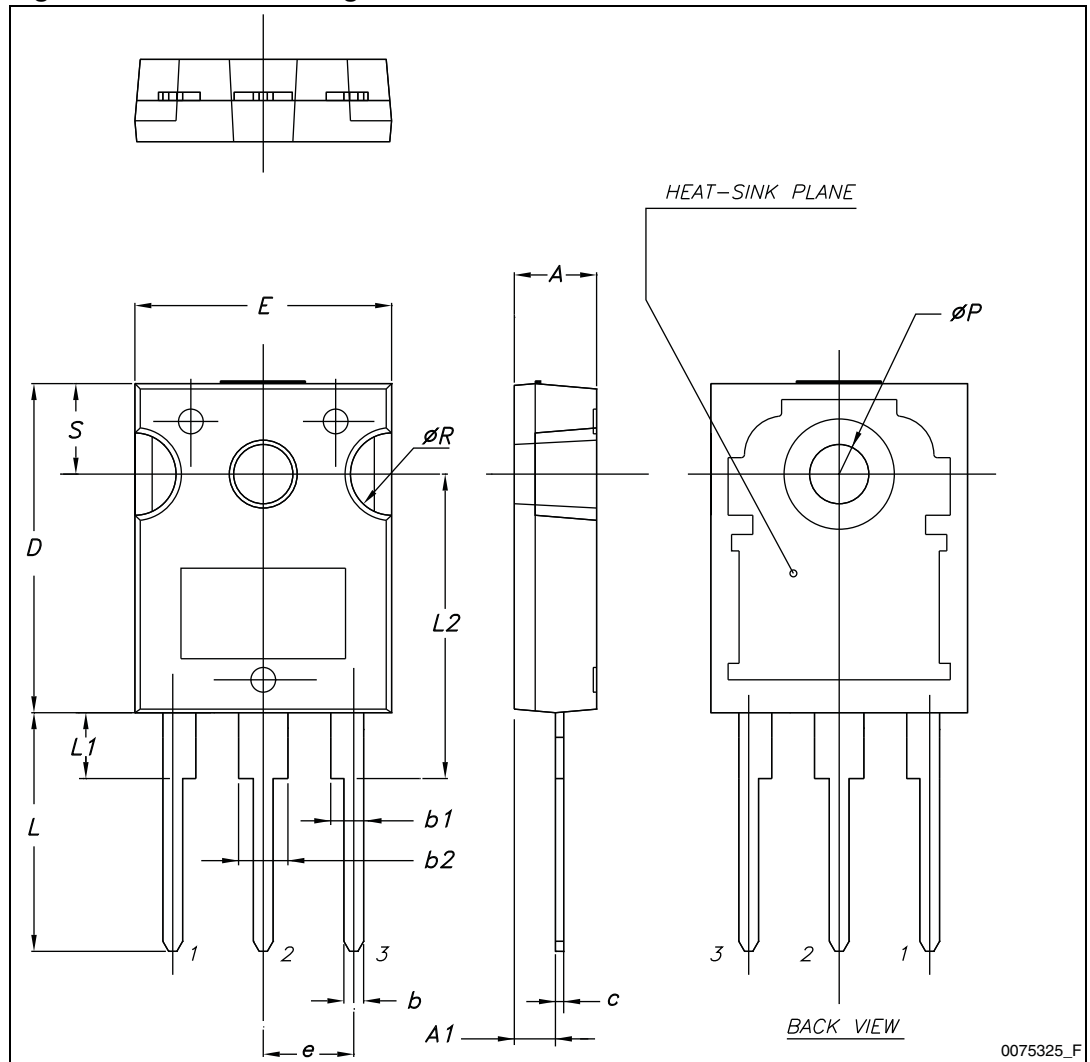
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. TO-247 mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.85 | | 5.15 |
| A1 | 2.20 | | 2.60 |
| b | 1.0 | | 1.40 |
| b1 | 2.0 | | 2.40 |
| b2 | 3.0 | | 3.40 |
| c | 0.40 | | 0.80 |
| D | 19.85 | | 20.15 |
| E | 15.45 | | 15.75 |
| e | | 5.45 | |
| L | 14.20 | | 14.80 |
| L1 | 3.70 | | 4.30 |
| L2 | | 18.50 | |
| ØP | 3.55 | | 3.65 |
| ØR | 4.50 | | 5.50 |
| S | | 5.50 | |

Figure 8. TO-247 drawing



0075325_F

5 Revision history

Table 9. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 30-Nov-2010 | 1 | First release |
| 18-Jul-2011 | 2 | <i>Section 4: Package mechanical data</i> has been updated. Minor text changes. |

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